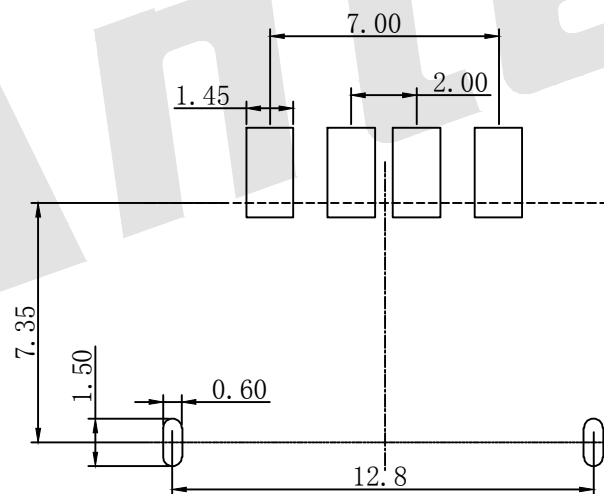
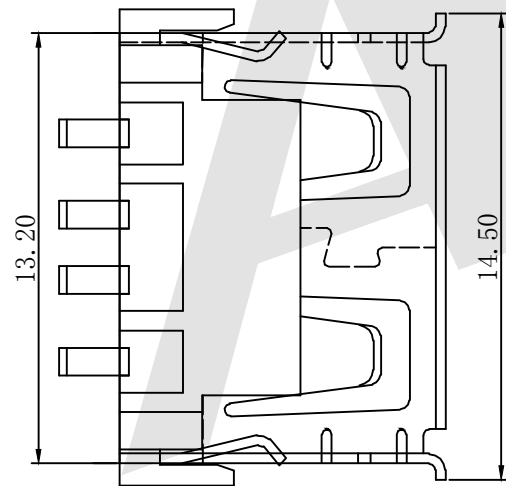
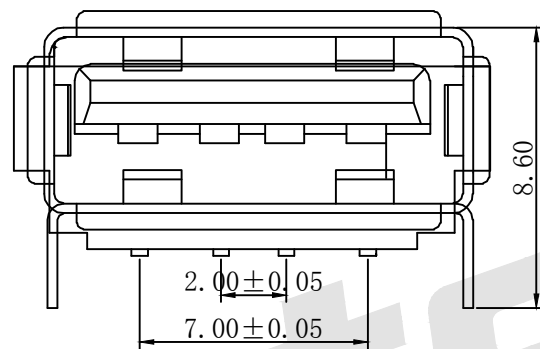
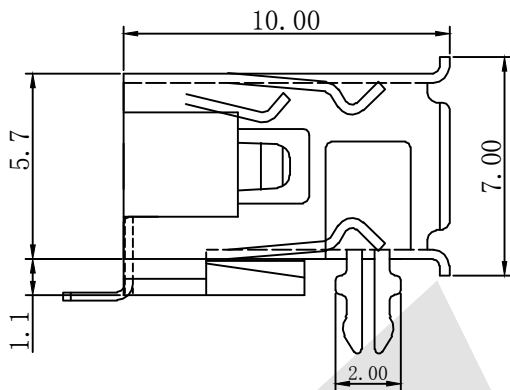


HSF



RECOMMENDED P. C. B LAYOUT

NOTES:

1. MATERIAL SPECIFICATION

- 1) INSULATION MATERIAL THERMOPLASTIC.
- 2) SHELL: COPPER ALLOY/SPCC, T: 0.30mm
PLATING: NICKEL
- 3) TERMINAL: COPPER ALLOY, T: 0.25mm
PLATING: GOLD/TIN PLATED.

2. ELECTRICAL CHARACTERISTIC:

- 1) INSULATION RESISTANCE: 1000MΩ MIN.
- 2) CONTACT RESISTANCE: 30MΩ MAX.
- 3) WITHSTANDING VOLTAGE: 500V AC.

3. MECHANICAL CHARACTERISTICS:

- 1) INSERTION FORCE: 3.57Kgf MAX
- 2) EXTRACTION FORCE: 1.02Kgf MIN.

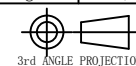
Ordering Code:

UAFM05 - X - X - X - X - X - X
 ① ② ③ ④ ⑤ ⑥ ⑦

- ① Series No:
- ② Shell Material:
B:Brass I:Iron
S:stainless steel
- ③ Insulator Material:
P:PBT+30%GF
L:LCP
- ④ Contact Material:
B:Brass
P:phosphor copper
- ⑤ Contact Plating
G0: Gold flash
G1: 3u" Gold
G2: 5u" Gold
G3: 10u" Gold
G4: 15u" Gold
G5: 30u" Gold
- ⑥ Color Insulator
A:White B:Black
- ⑦ Packing
A:Tray B:Bag
C:Tube D:Tape & Reel

Unless Otherwise specified tolerance
 X. ±0.35 X.XX: ±0.20
 X.X: ±0.25 X.XXX: ±0.15

SCALE: As Shown UNIT: mm
 DRAW Lv Xun Hua DATE 17/06/2019
 CHECK BobYang DATE 17/06/2019



Antenk® ANTENK ELECTRONICS CO.,LTD
 Http://www.antenk.com
 E-mail:sales@antenk.com

TITLE: USB A/F SMT 10.0mm with 2fork legs dip, standard version

DRAWING NO: UAFM05-XXXXXX

PRODUCT NO: UAFM05-XXXXXX

| REV | DESCRIPTION | DATE |
|-----|-------------|------|
| 1 | | |
| 2 | | |
| 3 | | |
| 4 | | |
| 5 | | |